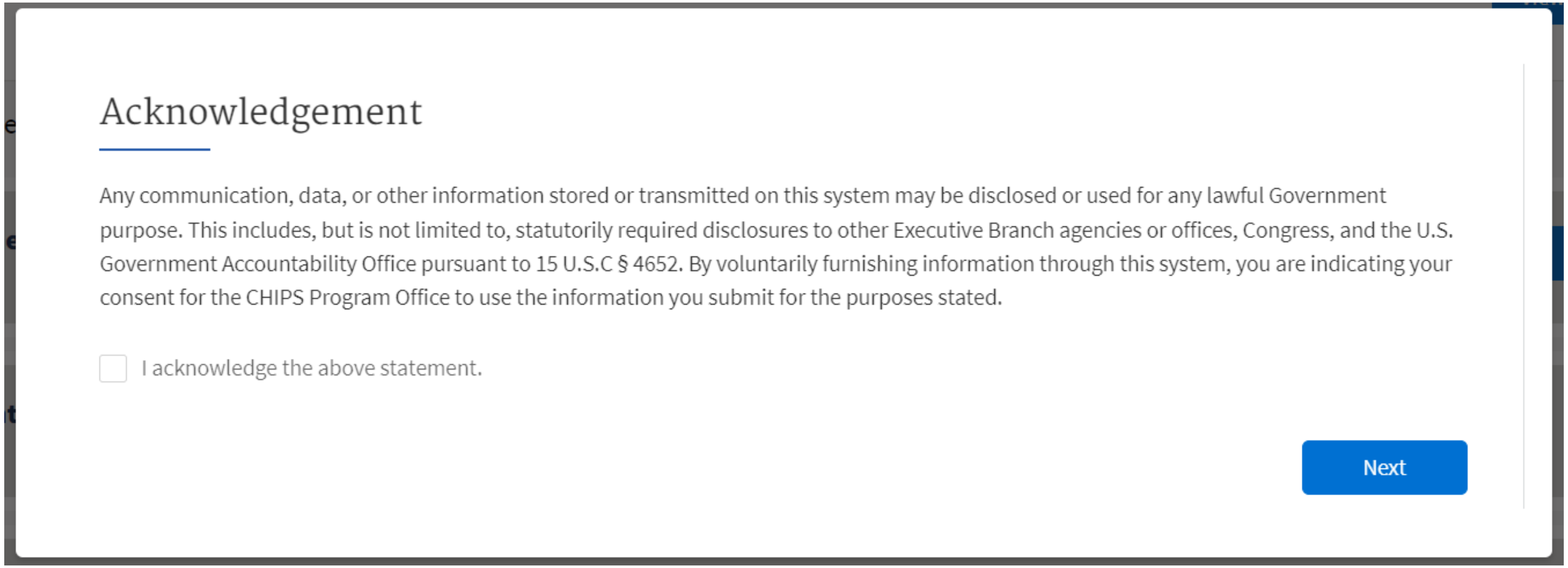
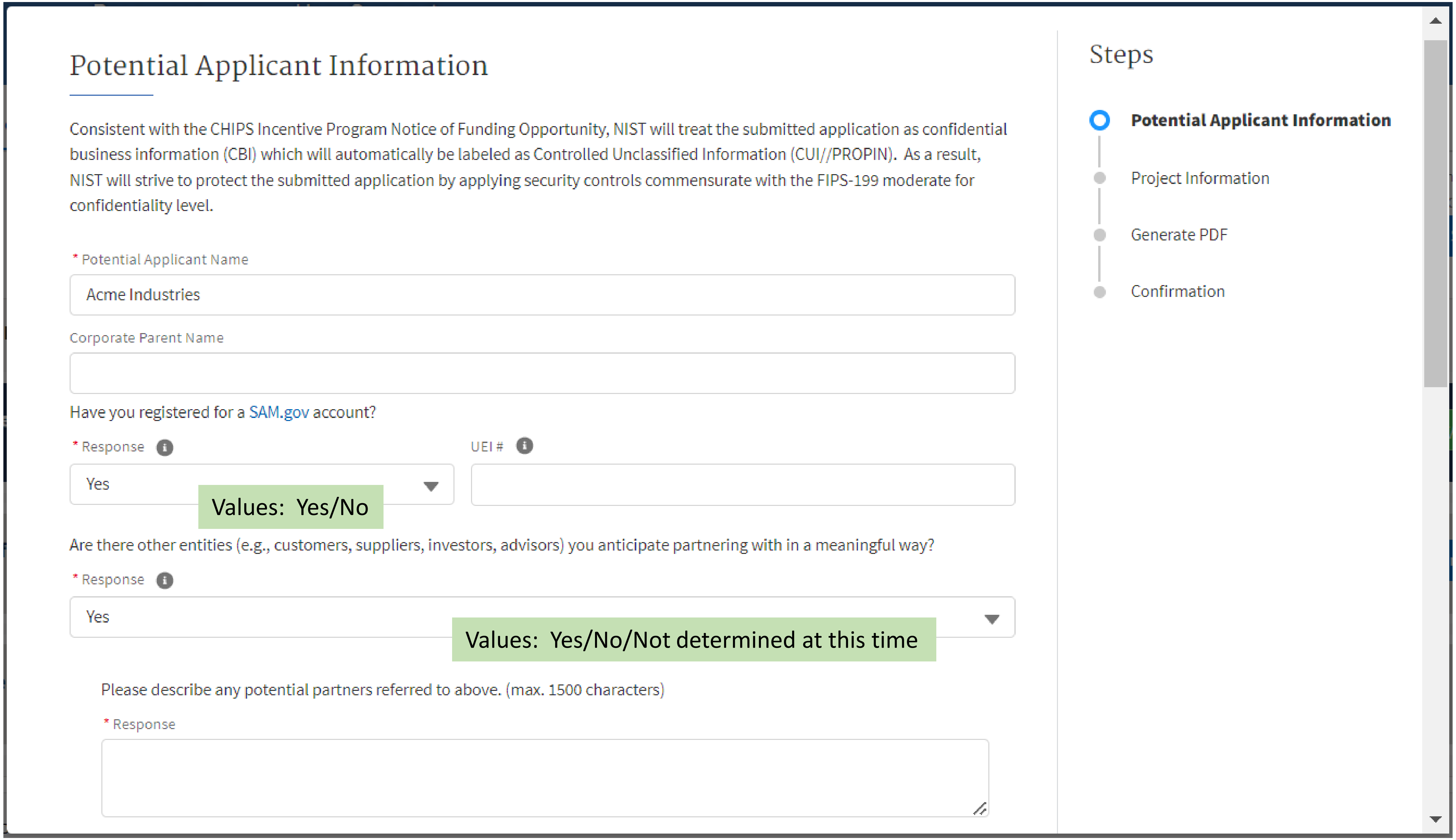


Acknowledgement

Any communication, data, or other information stored or transmitted on this system may be disclosed or used for any lawful Government purpose. This includes, but is not limited to, statutorily required disclosures to other Executive Branch agencies or offices, Congress, and the U.S. Government Accountability Office pursuant to 15 U.S.C § 4652. By voluntarily furnishing information through this system, you are indicating your consent for the CHIPS Program Office to use the information you submit for the purposes stated.

☐ I acknowledge the above statement.



Potential Applicant Information

Consistent with the CHIPS Incentive Program Notice of Funding Opportunity, NIST will treat the submitted application as confidential business information (CBI) which will automatically be labeled as Controlled Unclassified Information (CUI//PROPIN). As a result, NIST will strive to protect the submitted application by applying security controls commensurate with the FIPS-199 moderate for confidentiality level.

* Potential Applicant Name
Acme Industries

Corporate Parent Name

Have you registered for a SAM.gov account?

* Response: Yes

Values: Yes/No

UEI #

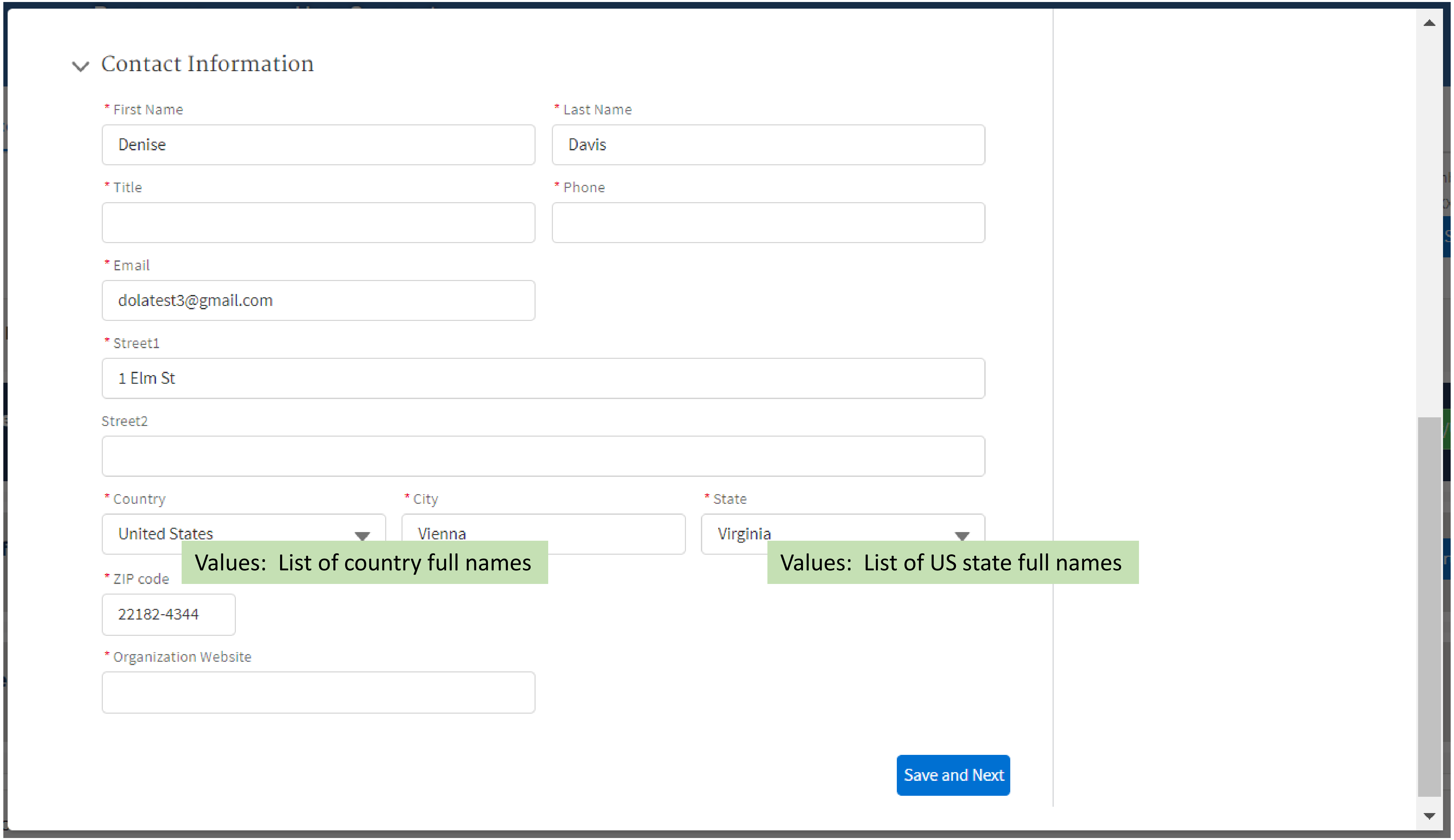
Are there other entities (e.g., customers, suppliers, investors, advisors) you anticipate partnering with in a meaningful way?

* Response: Yes

Values: Yes/No/Not determined at this time

Please describe any potential partners referred to above. (max. 1500 characters)

* Response



Contact Information

* First Name: Denise

* Last Name: Davis

* Title:

* Phone:

* Email: dolatest3@gmail.com

* Street1: 1 Elm St

Street2:

* Country: United States

* City: Vienna

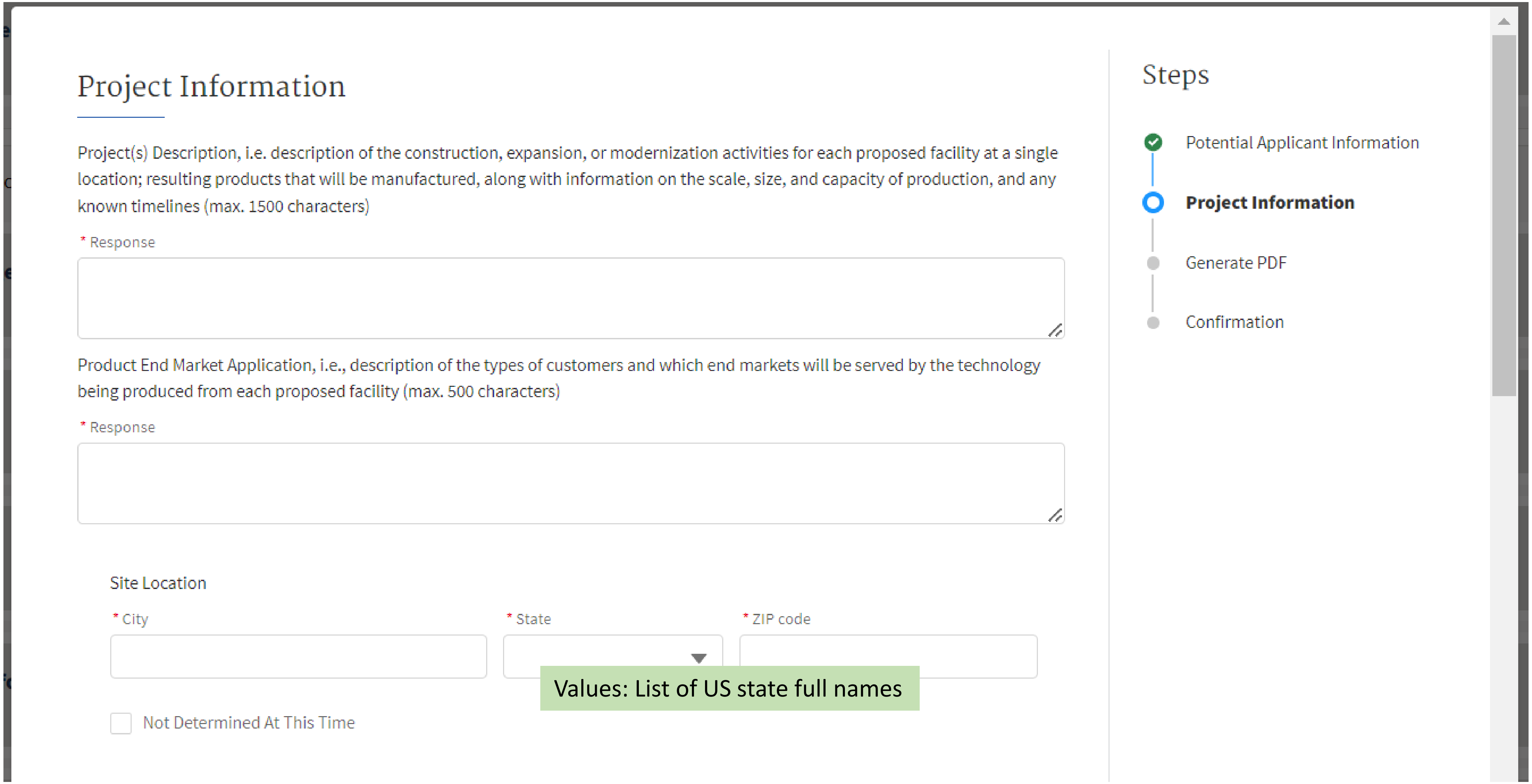
* State: Virginia

* ZIP code: 22182-4344

* Organization Website:

Values: List of country full names

Values: List of US state full names



Project Information

Project(s) Description, i.e. description of the construction, expansion, or modernization activities for each proposed facility at a single location; resulting products that will be manufactured, along with information on the scale, size, and capacity of production, and any known timelines (max. 1500 characters)

* Response

Product End Market Application, i.e., description of the types of customers and which end markets will be served by the technology being produced from each proposed facility (max. 500 characters)

* Response

Site Location

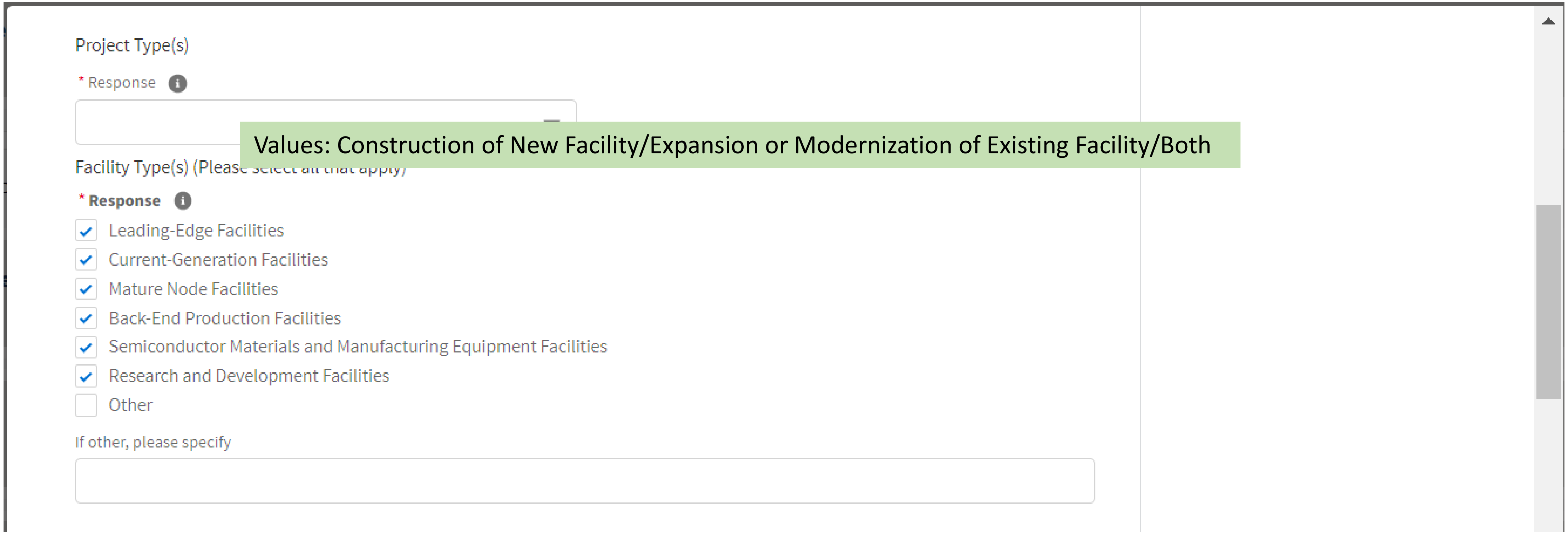
* City

* State

* ZIP code

☐ Not Determined At This Time

Values: List of US state full names



Project Type(s)

* Response

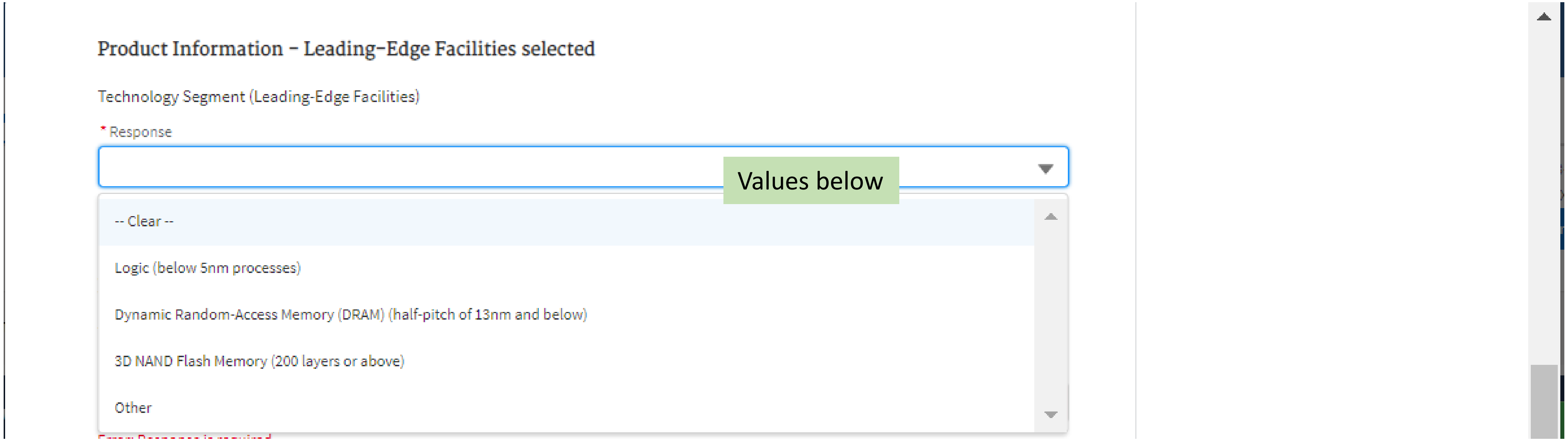
Values: Construction of New Facility/Expansion or Modernization of Existing Facility/Both

Facility Type(s) (Please select all that apply)

* **Response**

☑ Leading-Edge Facilities
☑ Current-Generation Facilities
☑ Mature Node Facilities
☑ Back-End Production Facilities
☑ Semiconductor Materials and Manufacturing Equipment Facilities
☑ Research and Development Facilities
☐ Other

If other, please specify



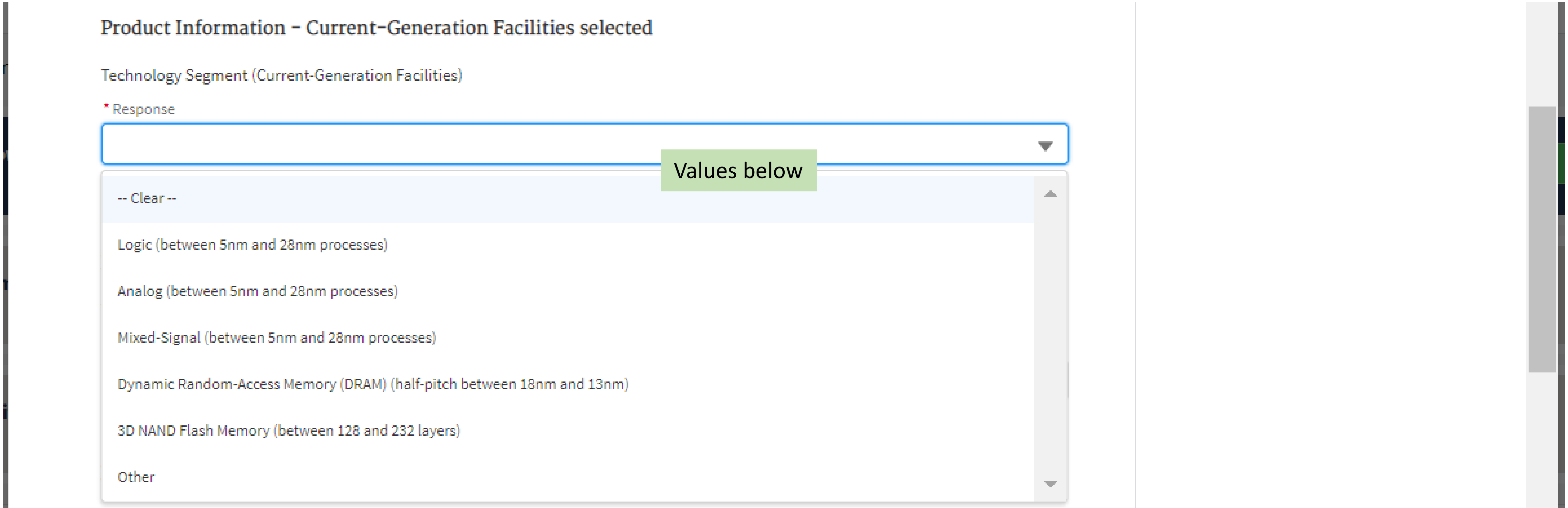
Product Information – Leading-Edge Facilities selected

Technology Segment (Leading-Edge Facilities)

* Response

Values below

- -- Clear --
- Logic (below 5nm processes)
- Dynamic Random-Access Memory (DRAM) (half-pitch of 13nm and below)
- 3D NAND Flash Memory (200 layers or above)
- Other



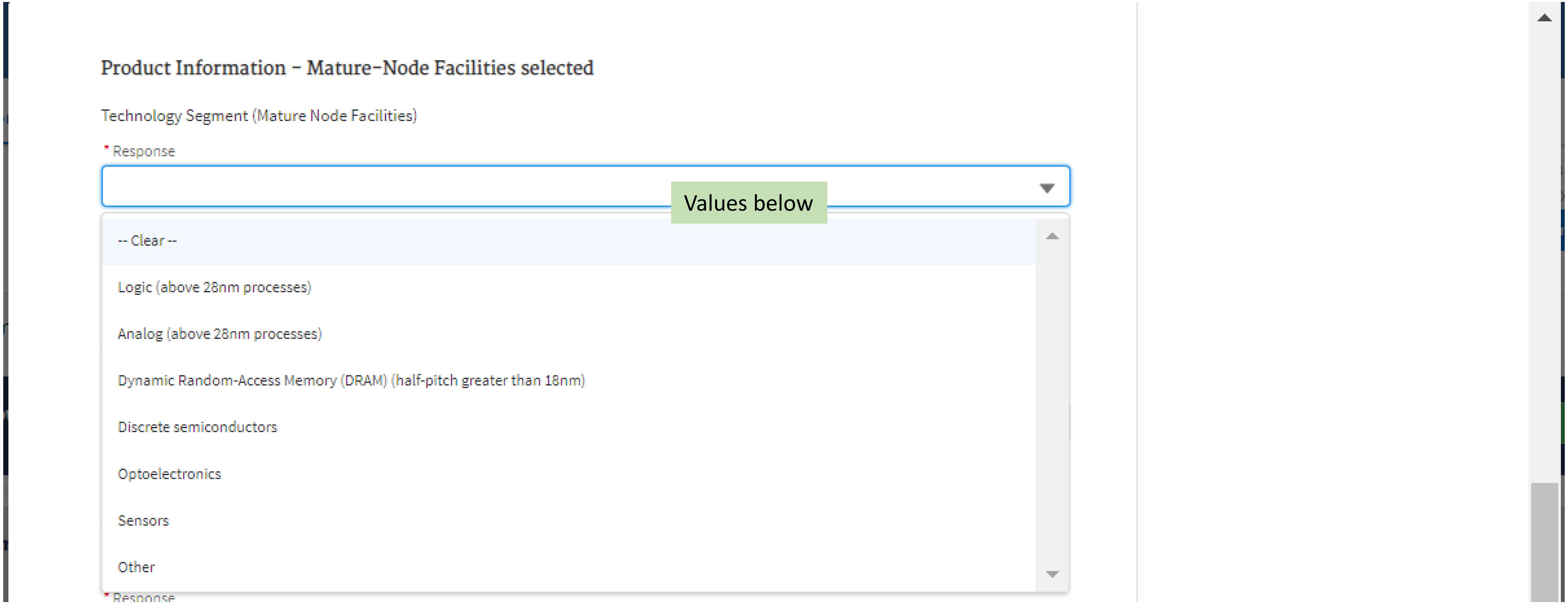
Product Information – Current-Generation Facilities selected

Technology Segment (Current-Generation Facilities)

* Response

Values below

- -- Clear --
- Logic (between 5nm and 28nm processes)
- Analog (between 5nm and 28nm processes)
- Mixed-Signal (between 5nm and 28nm processes)
- Dynamic Random-Access Memory (DRAM) (half-pitch between 18nm and 13nm)
- 3D NAND Flash Memory (between 128 and 232 layers)
- Other



Product Information – Mature-Node Facilities selected

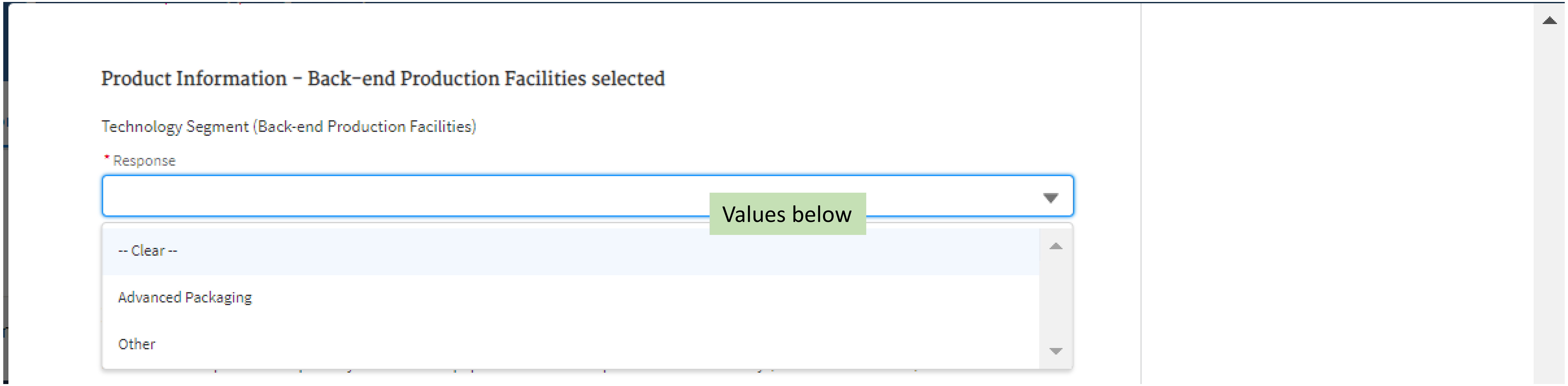
Technology Segment (Mature Node Facilities)

* Response

Values below

- -- Clear --
- Logic (above 28nm processes)
- Analog (above 28nm processes)
- Dynamic Random-Access Memory (DRAM) (half-pitch greater than 18nm)
- Discrete semiconductors
- Optoelectronics
- Sensors
- Other

* Response



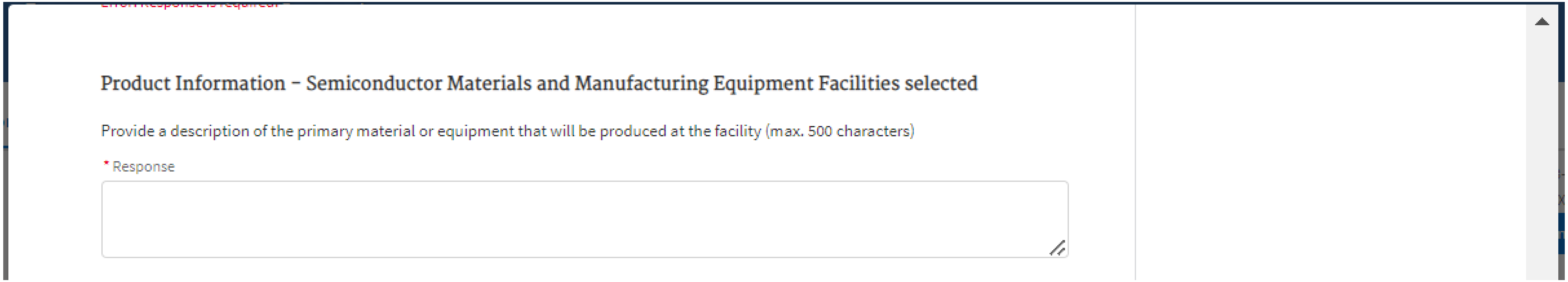
Product Information - Back-end Production Facilities selected

Technology Segment (Back-end Production Facilities)

* Response

Values below

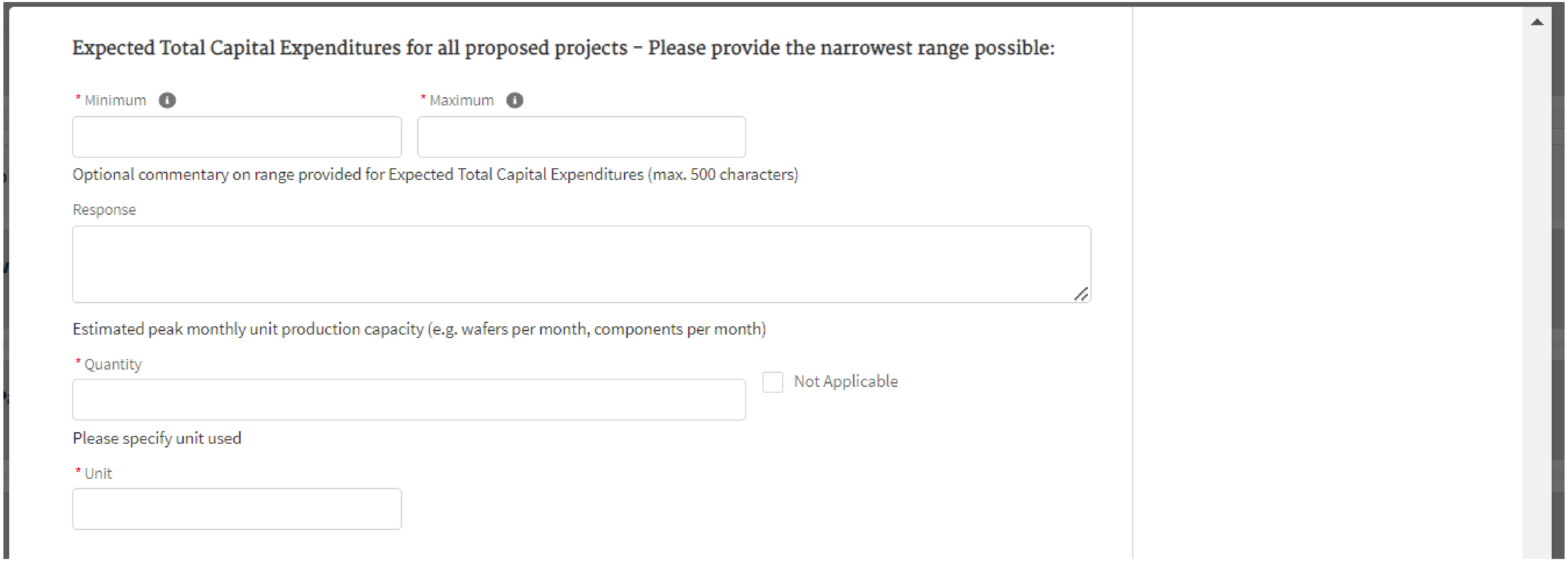
- -- Clear --
- Advanced Packaging
- Other



Product Information - Semiconductor Materials and Manufacturing Equipment Facilities selected

Provide a description of the primary material or equipment that will be produced at the facility (max. 500 characters)

* Response



Expected Total Capital Expenditures for all proposed projects – Please provide the narrowest range possible:

* Minimum

* Maximum

Optional commentary on range provided for Expected Total Capital Expenditures (max. 500 characters)

Response

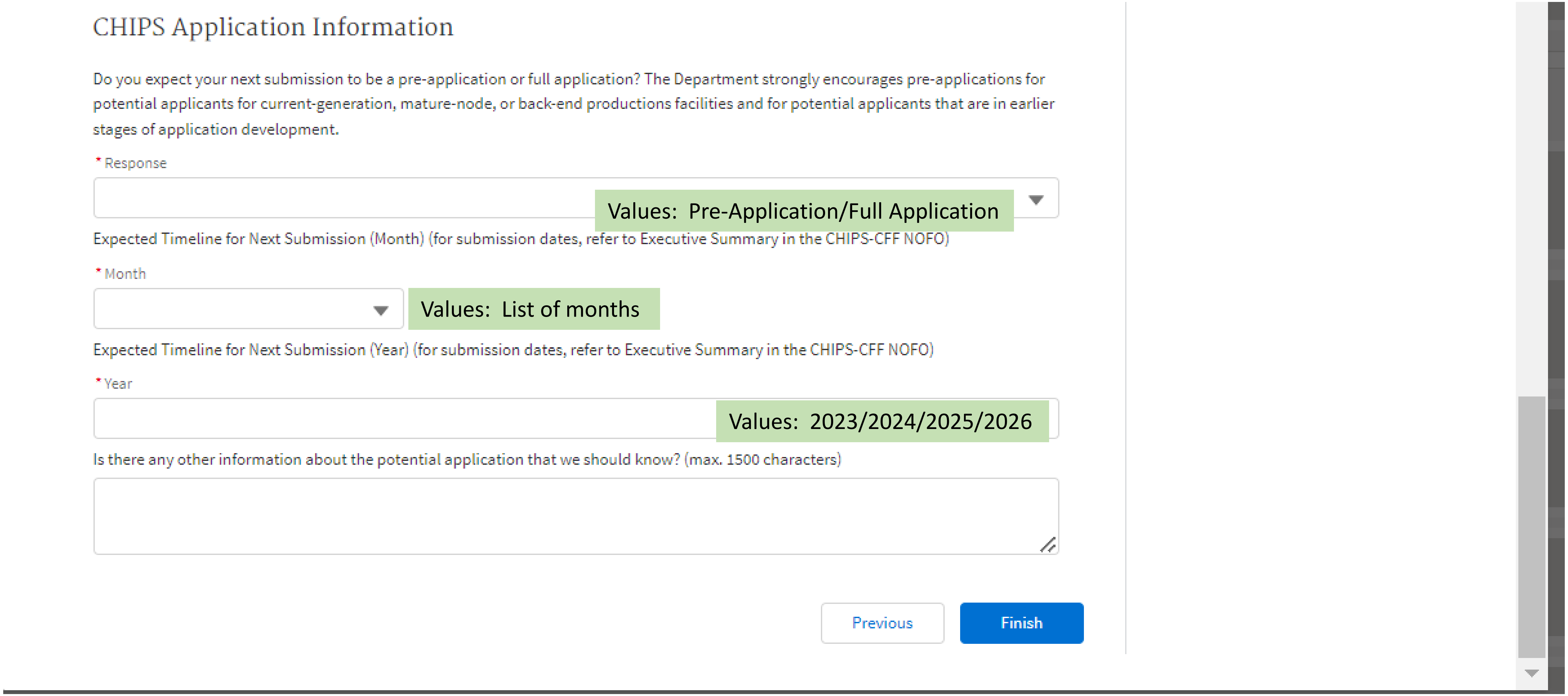
Estimated peak monthly unit production capacity (e.g. wafers per month, components per month)

* Quantity

☐ Not Applicable

Please specify unit used

* Unit



CHIPS Application Information

Do you expect your next submission to be a pre-application or full application? The Department strongly encourages pre-applications for potential applicants for current-generation, mature-node, or back-end productions facilities and for potential applicants that are in earlier stages of application development.

* Response

Values: Pre-Application/Full Application

Expected Timeline for Next Submission (Month) (for submission dates, refer to Executive Summary in the CHIPS-CFF NOFO)

* Month

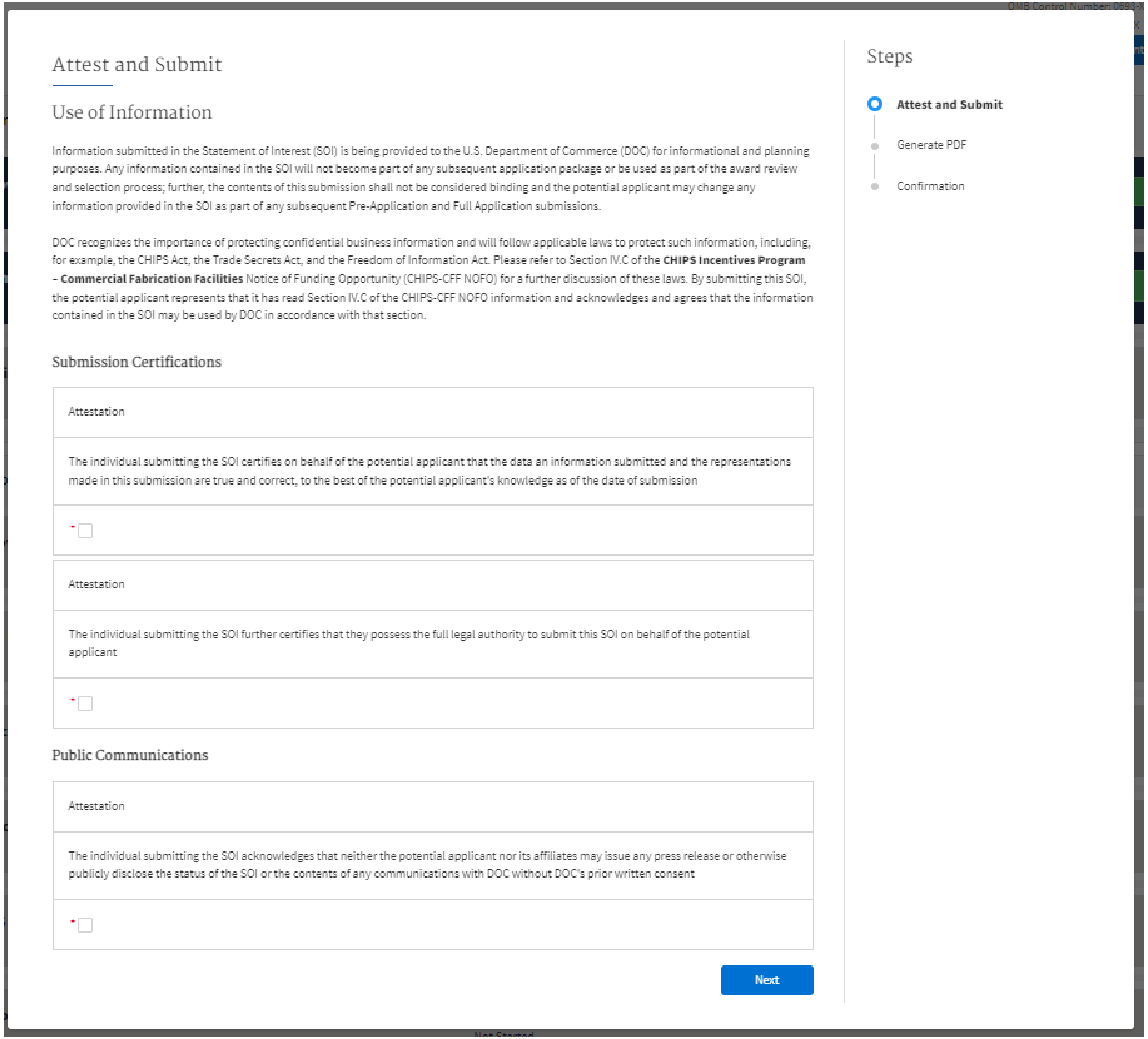
Values: List of months

Expected Timeline for Next Submission (Year) (for submission dates, refer to Executive Summary in the CHIPS-CFF NOFO)

* Year

Values: 2023/2024/2025/2026

Is there any other information about the potential application that we should know? (max. 1500 characters)



Attest and Submit

Use of Information

Information submitted in the Statement of Interest (SOI) is being provided to the U.S. Department of Commerce (DOC) for informational and planning purposes. Any information contained in the SOI will not become part of any subsequent application package or be used as part of the award review and selection process; further, the contents of this submission shall not be considered binding and the potential applicant may change any information provided in the SOI as part of any subsequent Pre-Application and Full Application submissions.

DOC recognizes the importance of protecting confidential business information and will follow applicable laws to protect such information, including, for example, the CHIPS Act, the Trade Secrets Act, and the Freedom of Information Act. Please refer to Section IV.C of the **CHIPS Incentives Program – Commercial Fabrication Facilities** Notice of Funding Opportunity (CHIPS-CFF NOFO) for a further discussion of these laws. By submitting this SOI, the potential applicant represents that it has read Section IV.C of the CHIPS-CFF NOFO information and acknowledges and agrees that the information contained in the SOI may be used by DOC in accordance with that section.

Submission Certifications

Attestation
The individual submitting the SOI certifies on behalf of the potential applicant that the data an information submitted and the representations made in this submission are true and correct, to the best of the potential applicant's knowledge as of the date of submission
* ☐
Attestation
The individual submitting the SOI further certifies that they possess the full legal authority to submit this SOI on behalf of the potential applicant
* ☐

Public Communications

Attestation
The individual submitting the SOI acknowledges that neither the potential applicant nor its affiliates may issue any press release or otherwise publicly disclose the status of the SOI or the contents of any communications with DOC without DOC's prior written consent
* ☐